



Thank you for attending the 2023 IEEE 73rd Electronic Components and Technology Conference, sponsored by the IEEE Electronics Packaging Society (EPS)!

We are pleased to inform you that this year's conference has been a resounding success. We want to thank all our authors, speakers, keynote speaker, invited panelists, plenary speakers, program committee members, exhibitors, sponsors, volunteers, attendees, and IEEE EPS sponsoring organization who contributed and helped us achieve this success!

Here are some conference statistics that we would like to share with you:

- 1,619 attendees, which, after the 2018 ECTC in San Diego, is the second-highest attended ECTC in its 73 years
- 379 technical papers, presented in 36 oral and 5 interactive presentation sessions, including one dedicated to students
- 8 Special Sessions, with a wide range of very interesting topics and international participation of experts from industry and academia
- 13 professional development courses attended by 325 participants
- Strong international representation of our technical program with speakers from 22 different countries all around the world
- Record level of industry support with 45 corporate sponsors and 49 sponsorships
- 117 Technology Corner exhibit booths – all exhibitors contacted so far have already committed to return next year!
- Several receptions & networking opportunities that we hope you enjoyed

We have made several changes to the format of ECTC this year. First, we made ECTC a four-day conference after our attendees showed up in force on Tuesday last year in San Diego. All Tuesday sessions in 2023 ECTC were packed with standing room only. The second change we made was introducing a conference-wide main stage event every morning on Wednesday, Thursday, and Friday. We officially opened the conference on Wednesday, the 31st of May, with our keynote speaker with more than a thousand colleagues in attendance. We presented two highly attended panels with international participation

on Thursday and Friday. These changes reduced the number of evening sessions, thereby creating more networking opportunities. The following special sessions brought different perspectives on technology trends, applications, business trends, transformational strategies, and career, diversity, and workforce development topics:

- **IEEE EPS President's Panel**

- Co-chaired by IEEE EPS President Kitty Pearsall of Boss Precision, US and David McCann of Lyte, and moderated by Amr Helmy of University of Toronto on "How can Photonics Enable the Bandwidth Densities with Lower Energy per Bit in Emerging SIP"

- **ECTC Plenary Session**

- Co-chaired by Kevin Gu of Metawave Corp. and Ivan Ndip of Fraunhofer IZM / Brandenburg University of Technology on "Digital Transformation – The Cornerstone of Future Semiconductor and Advanced Packaging Growth"

- **IEEE EPS Seminar**

- Co-chaired by Takashi Hisada of IBM and Yasumitsu Orii of Rapidus, Japan, on "The Future of High-density Substrates – Towards Submicron Technology"

- **ECTC Materials & Processing and Thermal/Mechanical Simulation & Characterization Technical Sub-Committees Special Session**

- Co-chaired by Tanja Braun of Fraunhofer IZM, Germany, and Przemyslaw Gromala of Bosch, Germany on "Advanced Packaging and HIR for Harsh Environment – Current Status and Opportunities"

- **ECTC Interconnections Technical Sub-Committee Special Session**

- Co-chaired by Thomas Gregorich (Infinera) and Chaoqi Zhang (Qualcomm), and moderated by Jan Vardaman of TechSearch International on "Copper Hybrid Bond Interconnections for Chip-On-Wafer Applications"

- **ECTC Photonics Technical Sub-Committee Special Session**

- Co-chaired by Stéphane Bernabé of CEA Leti, France, and Hiren Thacker of Cisco that covered "Photonic Integrated Circuit Packaging: Challenges, Pathfinding and Technology Adoption"

- **ECTC CHIPS Act Special Session**

- Co-chaired by Nancy Stoffel of GE Research, Jan Vardaman of TechSearch International, and William Chen of ASE on "Advanced Packaging Manufacturing in North America: Building the Ecosystem"

- **ECTC/ITHERM Diversity Panel**

- Co-chaired by Kim Yess of Brewer Science, Nancy Stoffel of GE Research, and Cristina Amon of University of Toronto, Canada, on "Diversifying our Technical Workforce to meet National Needs including the CHIPS Act Initiative"

- **ECTC Young Professionals Networking Panel**

- Chaired by Yan Liu of Medtronic, Inc., a networking panel focusing on career development for young professionals with the participation of IEEE EPS Board of Governors

The Heterogeneous Integration Roadmap Workshop, sponsored by the IEEE EPS took place again at our conference with another packed audience this year. Special thanks to the HIR committee for bringing another excellent workshop to ECTC.

Special thanks to our ECTC Keynote Speaker, Michael Manfra, Bill and Dee O'Brien Distinguished Professor of Physics and Astronomy at Purdue University and Scientific Director, Microsoft Quantum Lab West Lafayette, for his lecture on "Unlocking the Potential of Quantum Computers: Challenges and Opportunities in Electronic Devices, Interconnects, and Packaging." Prof. Manfra described the current state of quantum computing from a hardware perspective, listing the challenges and opportunities ranging from the basic choice of qubit platform, through scalable control and readout, to system architecture. He focused on what the packaging community can now innovate to make this revolutionary technology a reality. Following the keynote speech, a substantial Q&A session was held. Prof. Manfra's talk was captivating, inspirational, and intellectually stimulating.

We would like to thank our Corporate and Media Sponsors:

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2023, PCEA, Semiconductor Packaging News, Semiconductor Review, and Yole Group.

A big thank you to our volunteers, over 230 industry experts, Technical Program Committee members, Session Chairs, and Executive Committee members.

Photos taken at the conference are now available on Flickr and can be accessed [here](#).

Finally, after a successful ECTC 2023, we would like to hear back from you so we can learn and plan the best event for next year. What worked well, what needs improvement, and what did you miss?

[Please Answer Our Survey](#)

Next year's conference will be held 28-31 May 2024, at the Gaylord Rockies Resort and Convention Center, Denver, Colorado, USA. We look forward to your support to help make the 74th ECTC in 2024 a huge success.

On behalf of the entire Executive Committee, we thank you for participating at the 73rd ECTC and look forward to seeing you in Denver next year!

Sincerely,



Ibrahim Guven
General Chair, 2023 IEEE 73rd Electronic Components and Technology Conference
Associate Professor, Virginia Commonwealth University, Richmond, Virginia, USA.



Florian Herrault
Program Chair, 2023 IEEE 73rd Electronic Components and Technology Conference
Chief Technology Officer, Co-Founder, PseudolithIC, Inc, Santa Barbara, California, USA.

For more information on the 2023 ECTC visit www.ectc.net.

Also, see some of the 2022 ECTC [highlights](#).
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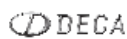
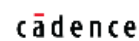


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